



Form 1449 (Modified)  <b>Information Disclosure Statement By Applicant</b>  (Use Several Sheets if Necessary)	<b>Atty Docket No.</b> ALTRP096/A1201  <b>Applicant:</b> Wen-Chou Vincent Wang, <i>et al.</i>  <b>Filing Date</b> November 20, 2003	<b>Application No.:</b> 10/719,451  <b>Group</b> 2815
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#### U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
Jbe	A1	6,617,683	09/2003	Lebonheur, <i>et al.</i>			
	A2	6,504,242	01/2003	Deppisch, <i>et al.</i>			
	A3	6,756,685	06/2004	Tao, Tetsuya			
	A4	6,262,489	07/2001	Koors, <i>et al.</i>			
	A5	6,773,963	08/2004	Houle, Sabina J.			
	A6	5,909,056	06/1999	Mertol, Atila			
	A7	6,091,603	07/2000	Daves, <i>et al.</i>			
	A8	6,472,762	10/2002	Kutlu, Zafer S.			
	A9	6,744,132	06/2004	Alcoe, <i>et al.</i>			
Jbe	A10	6,103,550	08/2000	Camenforte, <i>et al.</i>			

#### Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No

#### Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
Jbe	C1	U.S. Patent Application, Serial No.: 10/849,651 filed May 19, 2004 entitled: <i>Low Stress And Warpage Laminate Flip Chip BGA Package</i>
Examiner <i>Jasmine Clark</i>		Date Considered <i>03/04/05</i>

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.